ABSOLUTE MAXIMUM RATINGS

V _{DD} to GND	0.3V to +6V
OUT_, SCLK, DIN, $\overline{\text{CS}}$, REF to GND	0.3 to (V _{DD} +0.3V)
Maximum Continuous Current Into Any Pin	
Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
8-Pin µMAX (derate 4.6 mW/°C above +70)°C)362mW

Operating Temperature Range	40°C to +125°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = +2.7 \text{V to } +5.5 \text{V}, \text{GND} = 0, V_{REF} = V_{DD}, R_L = 5 \text{k}\Omega, C_L = 200 \text{pF}, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are } V_{DD} = +5 \text{V}, T_A = +25 ^{\circ}\text{C}.)$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
STATIC ACCURACY (Note 1)	•		· ·			
Resolution N			10			Bits
Intergral Nonlinearity Error	INL	(Note 2)		±0.5	±4	LSB
Differential Nonlinearity Error	DNL	Guaranteed monotonic (Note 2)			±1	LSB
Zero-Code Error	OE	Code = 000		0.4	1.5	% of FS
Zero-Code Error Tempco				2.3		ppm/°C
Gain Error	GE	Code = 3FF hex			±3	% of FS
Gain-Error Tempco				0.26		ppm/°C
Power-Supply Rejection Ratio	PSRR	Code = 3FF hex, ΔV_{DD} = ±10%		58.8		dB
REFERENCE INPUT						
Reference Input Voltage Range	V _{REF}		0		V_{DD}	V
Reference Input Impedance	Poee	In operation	64	90	126	kΩ
neierence input impedance	R _{REF}	In power-down mode		2		МΩ
Reference-Down Reference Current		In power-down mode (Note 3)		1	10	μΑ
DAC OUTPUT	•					•
Output Voltage Range		No load (Note 4)	0		V _{DD}	V
DC Output Impedance		Code = 200 hex		0.8		Ω
Short-Circuit Current		$V_{DD} = +3V$		15		A
Short-Circuit Current		$V_{DD} = +5V$		48		mA
Males He Times		$V_{DD} = +3V$		8		
Wake-Up Time		$V_{DD} = +5V$		8		μs
Output Leakage Current		Power-down mode = output high impedance	±18			nA

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = +2.7V \text{ to } +5.5V, \text{GND} = 0, V_{REF} = V_{DD}, R_L = 5k\Omega, C_L = 200pF, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are } V_{DD} = +5V, T_A = +25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DIGITAL INPUTS (SCLK, DIN, \overline{C}	S)		•			
Input High Voltage	V _{IH}	V _{DD} = +3V, +5V	0.7 x V _{DD}			V
Input Low Voltage	V _{IL}	$V_{DD} = +3V, +5V$			0.3 x V _{DD}	V
Input Leakage Current	I _{IN}	Digital inputs = 0 or V _{DD}		±0.1	±1	μΑ
Input Capacitance				5		pF
DYNAMIC PERFORMANCE						
Voltage-Output Slew Rate	SR			0.5		V/µs
Voltage-Output Settling Time		100 hex to 300 hex (Note 5)		4	10	μs
Digital Feedthrough		All digital inputs from 0 to V _{DD}		0.1		nV-s
Digital-Analog Glitch Inpulse		Major carry transition (code 1FF hex to code 200 hex)		12		nV-s
DAC-to-DAC Crosstalk						nV-s
POWER REQUIREMENTS						
Supply Voltage Range	V _{DD}		2.7		5.5	V
Cupply Current with No. Lood	loo	All digital inputs at 0 or V _{DD} = 3.6V		112	205	
Supply Current with No Load	IDD	All digital inputs at 0 or V _{DD} = 5.5V		135	215	μA
Power-Down Supply Current	I _{DDPD}	All digital inputs at 0 or V _{DD} = 5.5V		0.29	1	μΑ

TIMING CHARACTERISTICS

 $(V_{DD} = 2.7V \text{ to } 5.5V, \text{GND} = 0, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.})$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SCLK Clock Frequency	fsclk		0		20	MHz
SCLK Pulse Width High	^t CH		25			ns
SCLK Pulse Width Low	t _{CL}		25			ns
CS Fall to SCLK Rise Setup Time	tcss		10			ns
SCLK Fall to CS Rise Setup Time	tcsh		10			ns
DIN to SCLK Fall Setup Time	t _{DS}		15			ns
DIN to SCLK Fall Hold Time	tDH		0		•	ns
CS Pulse Width High	tcsw		80			ns

Note 1: DC specifications are tested without output loads.

Note 2: Linearity guaranteed from code 29 to code 995.

Note 3: Limited with test conditions.

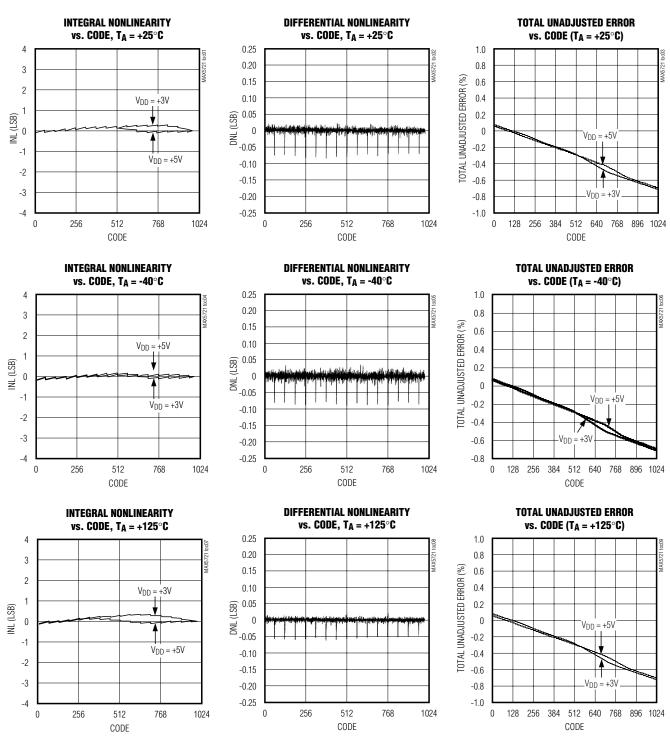
Note 4: Offset and gain error limit the FSR.

Note 5: Guaranteed by design.



Typical Operating Characteristics

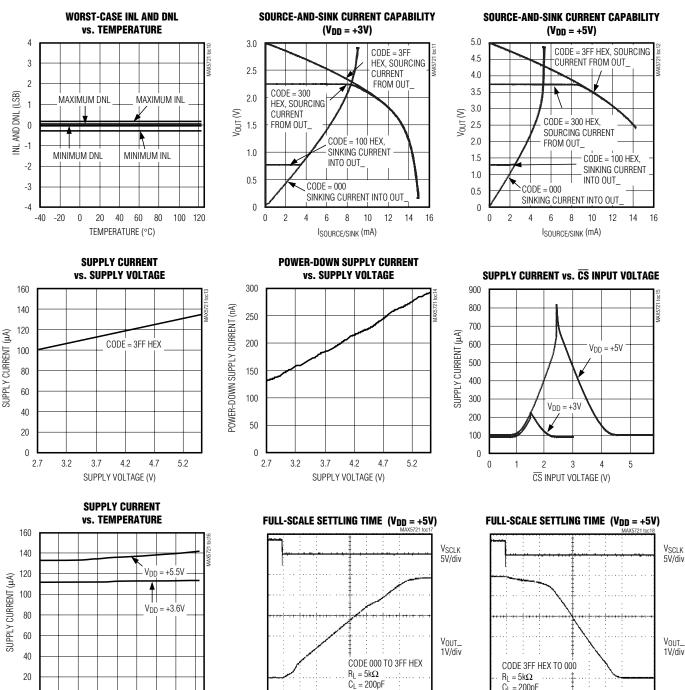
 $(V_{REF} = V_{DD}, T_A = +25^{\circ}C, unless otherwise noted.)$



4 ______ **/\|/\|X\|/\|**

Typical Operating Characteristics (continued)

 $(V_{REF} = V_{DD}, T_A = +25^{\circ}C, unless otherwise noted.)$



1µs/div

NIXIN

-40 -20

20 40 60

TEMPERATURE (°C)

80

100 120

 $C_1 = 200pF$

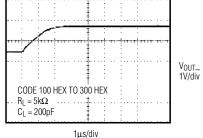
1µs/div

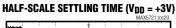
Typical Operating Characteristics (continued)

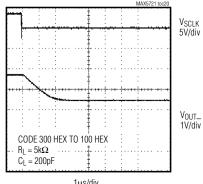
 $(V_{REF} = V_{DD}, T_A = +25^{\circ}C, unless otherwise noted.)$



HALF-SCALE SETTLING TIME $(V_{DD} = +3V)$

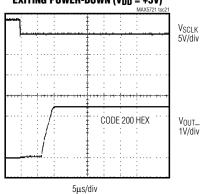




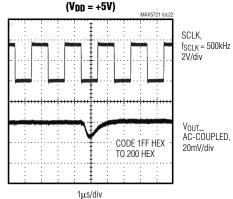


1μs/div

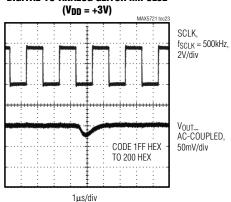
EXITING POWER-DOWN $(V_{DD} = +5V)$



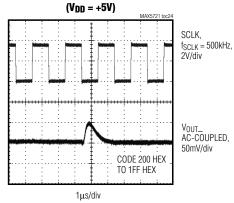
DIGITAL-TO-ANALOG GLITCH IMPULSE



DIGITAL-TO-ANALOG GLITCH IMPULSE



DIGITAL-TO-ANALOG GLITCH IMPULSE

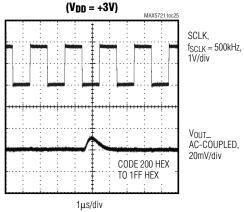


MIXIM

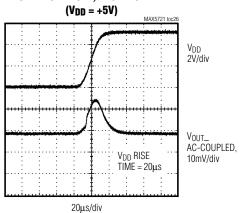
Typical Operating Characteristics (continued)

($V_{REF} = V_{DD}$, $T_{A} = +25$ °C, unless otherwise noted.)

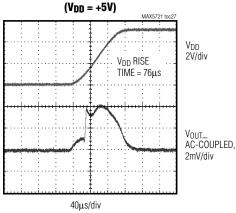
DIGITAL-TO-ANALOG GLITCH IMPULSE



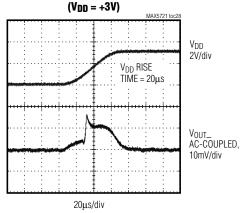
POWER-ON RESET, FAST RISE TIME



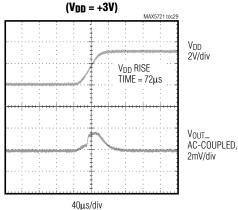
POWER-ON RESET, SLOW RISE TIME



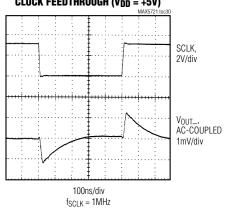
POWER-ON RESET, FAST RISE TIME



POWER-ON RESET, SLOW RISE TIME

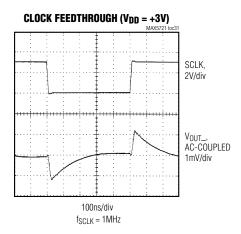


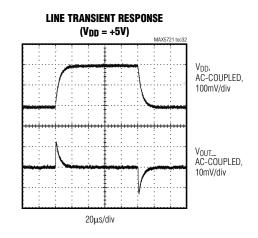
CLOCK FEEDTHROUGH ($V_{DD} = +5V$)

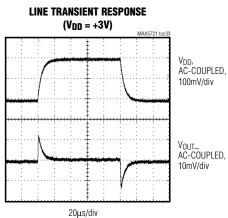


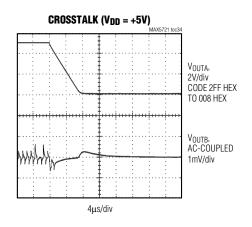
Typical Operating Characteristics (continued)

($V_{REF} = V_{DD}$, $T_A = +25$ °C, unless otherwise noted.)









Pin Description

PIN	NAME	FUNCTION
1	V _{DD}	Power-Supply Input
2	GND	Ground
3	CS	Chip-Select Input
4	SCLK	Serial Clock Input
5	DIN	Serial Data Input
6	REF	External Reference Voltage Input
7, 8	OUTA, OUTB	DAC Voltage Outputs. Power-on reset sets DAC registers to zero, and internally connects OUT to GND with $100 k\Omega$ resistor.

Detailed Description

The MAX5721 contains two 10-bit, voltage-output, lowpower digital-to-analog converters (DACs). Each DAC employs a resistor string architecture that converts a 10-bit digital input word to an equivalent analog output voltage proportional to the applied reference voltage. The MAX5721 shares one reference input (REF) between both DACs. The MAX5721 includes rail-to-rail output buffer amplifiers for each DAC, and input logic for simple microprocessor (µP), and CMOS interfaces. The power-supply range is from +2.7V to +5.5V (Functional Diagram). The MAX5721's reference input accepts a voltage range from 0 to VDD. In power-down mode the reference input is high impedance. The MAX5721 is compatible with the 3-wire SPI, QSPI, MICROWIRE, and DSP serial interface with Schmitt-triggered logic inputs.

Reference Input and DAC Output Range

The reference input accepts positive DC and AC signals. The voltage at REF sets the full-scale output voltage of both DACs. The reference input voltage range is 0 to VDD. The impedance at REF is $90k\Omega$. The voltage at REF can vary from GND to VDD. The output voltages (VOUT_) are represented by a digitally programmable voltage source as:

$$VOUT = (VREF \times D) / 2^{10}$$

where D is the decimal equivalent of binary DAC input code ranging from 0 to 1023. V_{REF} is the voltage at REF.

Output Buffer Amplifiers

All DACs are internally buffered at the output. The buffer amplifiers have both rail-to-rail common mode and (GND to VREF) output voltage range. The buffers are unity-gain stable with $C_L=200 pF$ and $R_L=5 k\Omega$. Buffer amplifiers are disabled during power-up and individual DAC outputs are shorted to GND through a $100 k\Omega$ resistor. Buffer amplifiers can individually or altogether be powered-down by programming the input register control bits. During power down, contents of the input and DAC registers remain the same. On wake-up all DAC outputs are restored to their pre-power-down voltage values.

Power-Down Mode

In power-down mode, the DAC outputs are programmed to one of three output states, $1k\Omega$, $100k\Omega$, or floating (Table 1). The REF input is high impedance (2M Ω typ) to conserve current drain from the system reference; therefore, the system reference does not have to be powered-down. The DAC outputs return to the values contained in the registers when brought out of power-down. The recovery time, from total power-

down to power-up, is 8µs. This extra time is needed to allow the internal bias to wake-up. Power-down mode reduces current consumption to 0.5µA.

3-Wire Serial Interface

The MAX5721 digital interface is a standard 3-wire connection compatible with SPI/QSPI/MICROWIRE/DSP interfaces. The chip-select input $\overline{(CS)}$ frames the serial data loading at DIN. Immediately following \overline{CS} high-to-low transition, the data is shifted synchronously and latched into the input register on the falling edge of the serial clock input (SCLK). After 16 bits have been loaded into the serial input register, it transfers its contents to the DAC latch. \overline{CS} may then either be held low or brought high. \overline{CS} must be brought high for a minimum of 80ns before the next write sequence, since a write sequence is initiated on a falling edge of \overline{CS} . Not keeping \overline{CS} low during the first 15 SCLK cycles discards input data. The serial clock (SCLK) can idle either high or low between transitions.

The MAX5721 has two internal registers per DAC, the input register and the DAC register. The input register holds the data that is waiting to be shifted to the DAC register. Both input registers can be loaded without updating the output. This function is useul when both outputs need to be updated at the same time. The input register can be made transparent. When the input register is transparent, the data written into DIN loads directly to the DAC register and the output is updated. The DAC output is not updated until data is written to the DAC register. See Table 2 for a list of serial-interface programming commands.

Power-On Reset (POR)

The MAX5721 has an internal POR circuit. At power-up all DACs are powered-down and OUT_ is terminated to GND through $100 \mathrm{k}\Omega$ resistors. Contents of input and DAC registers are cleared to all zero. An 8µs recovery time after issuing a wake-up command is needed before writing to the DAC registers. Power-down mode control commands can be applied immediately with no recovery time.

C3-C0 are control bits. The data bits D9 to D0 are in straight binary format. Set bits S1 and S0 to zero. All zeros correspond to zero scale and all ones correspond to full scale.

Digital Inputs

The digital inputs are compatible with CMOS logic. In order to save power and reduce input to output coupling, SCLK and DIN input buffers are powered down immediately after completion of shifting 16 bits into the input shift register. A high to low transition at $\overline{\text{CS}}$ powers up SCLK and DIN input buffers.

Table 1. Power-Down Mode Control

1		TENDED NTROL		DATA BITS				DESCRIPTION	FUNCTION		
СЗ	C2	C1	C0	D9-D3	D2	D1	D0	S1	S0		
1	1	1	1	Χ	0	0	0	0	0	DAC A	DAC O/P, wake-up
1	1	1	1	Χ	0	0	0	0	1	DAC A	Floating output
1	1	1	1	Χ	0	0	0	1	0	DAC A	Output is terminated with $1k\Omega$
1	1	1	1	Χ	0	0	0	1	1	DAC A	Output is terminated with 100kΩ
1	1	1	1	Χ	0	0	1	0	0	DAC B	DAC O/P, wake-up
1	1	1	1	Χ	0	0	1	0	1	DAC B	Floating output
1	1	1	1	Χ	0	0	1	1	0	DAC B	Output is terminated with $1k\Omega$
1	1	1	1	Χ	0	0	1	1	1	DAC B	Output is terminated with 100kΩ
1	1	1	1	Χ	1	0	0	0	0	DAC A-B	DAC O/P, wake-up
1	1	1	1	Χ	1	0	0	0	1	DAC A-B	Floating output
1	1	1	1	Χ	1	0	0	1	0	DAC A-B	Output is terminated with 1kΩ
1	1	1	1	Х	1	0	0	1	1	DAC A-B	Output is terminated with 100k Ω

X = Don't Care

CONT	CONTENTS OF INPUT SHIFT REGISTER														
D15 (D15 (MSB) D0 (LSB)														
C3	C2	C1	C0	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	S1	S0

Figure 1. 16-Bit Input Word

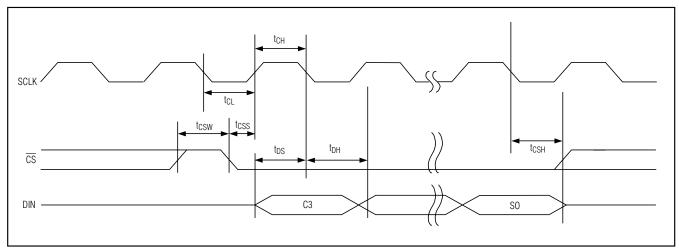


Figure 2. Timing Diagram

0 ______ **/\| X\| /\|**

Table 2. Serial-Interface Programming Commands

	CONTROL			DATA BITS		DAC	FUNCTION
C3	C2	C1	CO	D9-D0	S1-S0	DAC	FUNCTION
0	0	0	0	Χ	Χ	А	Input register transparent, data shifted directly to DAC register, OUTA updated
0	0	0	1	Χ	Χ	В	Input register transparent, data shifted directly to DAC register, OUTB updated
0	1	0	0	Χ	Χ	Α	Data shifted to input register, OUTA unchanged
0	1	0	1	Χ	Χ	В	Data shifted to input register, OUTB unchanged
1	0	0	0	Χ	Χ	Α	Shift data from input register to DAC register, OUTA updated
1	0	0	1	Χ	Χ	В	Shift data from input register to DAC register, OUTB updated
1	1	0	0	X	Х	A-B	Input registers transparent, data shifted directly to DAC registers, OUTA and OUTB updated
1	1	0	1	Χ	Χ	A-B	Data shifted to input registers, OUTA and OUTB unchanged
1	1	1	0	Χ	Χ	A-B	Shift data from input registers to DAC registers, OUTA and OUTB updated

X = Don't Care

Applications Information

Unipolar Output

The typical application circuit (Figure 3) shows the MAX5721 configured for a unipolar output, where the output voltages and the reference inputs have the same polarity. Table 3 lists the unipolar output codes.

Bipolar Output

The MAX5721 can be configured for bipolar operation using a dual supply op amp (Figure 4). The transfer function for bipolar operation is:

$$V_{OUT} = V_{REF} \left[\left(\frac{2D}{1024} \right) - 1 \right]$$

Figure 3. Typical Operating Circuit, Unipolar Output

where DB is the decimal value of the DACs binary input code. Table 4 shows digital codes (offset binary) and corresponding output voltages for the circuit in Figure 4.

Power Supply and Layout Considerations

Careful PC board layout is important for optimal system performance. To reduce noise injection and digital feed-through, keep analog and digital signals separate. Ensure that that the return path from GND to the supply ground is short and low impedance. Use a ground plane. Bypass V_{DD} to GND with a $0.1\mu F$ capacitor as close as possible to V_{DD} .

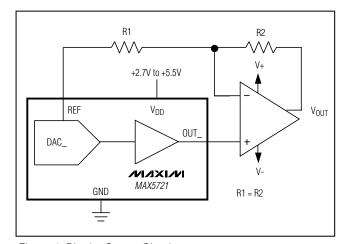


Figure 4. Bipolar Output Circuit

Table 3. Unipolar Code Table

DAC CONTENTS	ANALOG OUTPUT
1111 1111 1100	$+V_{REF} \left(\frac{1023}{1024} \right)$
1000 0000 0100	$+V_{REF}\left(\frac{513}{1024}\right)$
1000 0000 0000	+ VREF 2
0111 1111 1100	$+V_{REF}\left(\frac{511}{1024}\right)$
0000 0000 0100	$+V_{REF}\left(\frac{1}{1024}\right)$
0000 0000 0000	0

Table 4. Bipolar Code Table

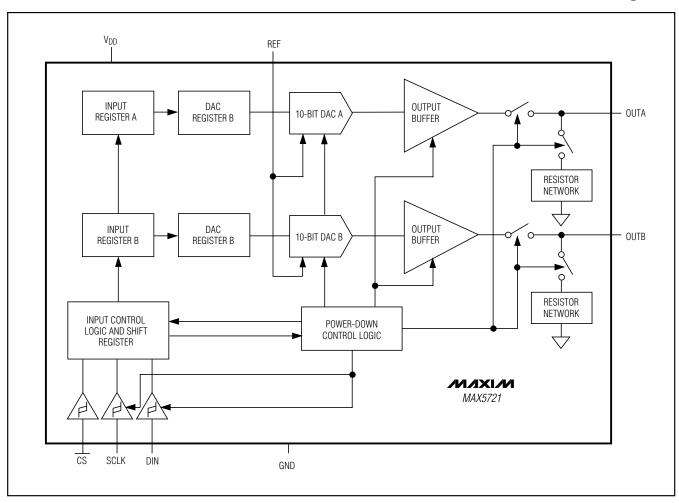
DAC CONTENTS	ANALOG OUTPUT
1111 1111 1100	$+V_{REF}\left(\frac{511}{512}\right)$
1000 0000 01000	$+V_{REF}\left(\frac{1}{512}\right)$
1000 0000 0000	0
0111 1111 11100	$-V_{REF}\left(\frac{1}{512}\right)$
0000 0000 0100	$-V_{REF}\left(\frac{511}{512}\right)$
0000 0000 0000	-V _{REF}

Chip Information

TRANSISTOR COUNT: 7737

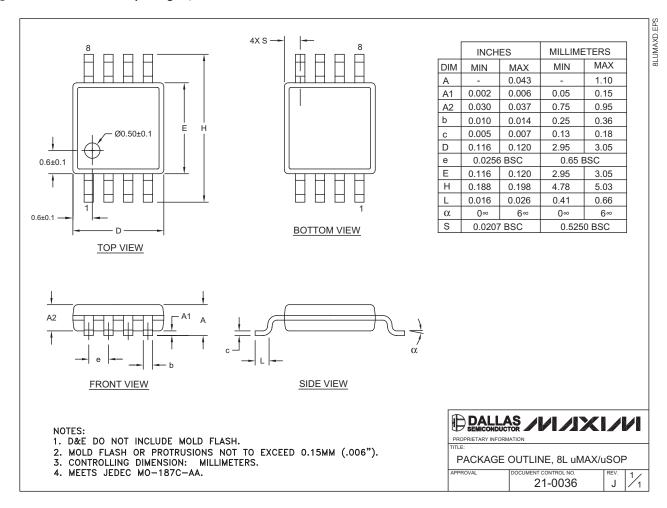
PROCESS: BICMOS

Functional Diagram



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



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